

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT5697383

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
LI-SHING CHOU	08/13/2019
CHIH-CHAO YANG	08/13/2019
CHI-SAN CHEN	08/13/2019
CHIH-JUNG WENG	08/13/2019
HENG-YI TSAI	08/13/2019
RECEIVING PARTY DATA	
Name:	INDUSTRIAL TECHNOLOGY RESEARCH INSTITUTE
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City:	HSINCHU
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Postal Code:	31040
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16551755
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SIGNATURE:	/Belinda Lee/
DATE SIGNED:	09/01/2019
Total Attachments: 2	
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ASSIGNMENT

WHEREAS,

**1.Li-Shing Chou
3.Chi-San Chen
5.Heng-Yi Tsai**

**2.Chih-Chao Yang
4.Chih-Jung Weng**

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **METAL MATRIX COMPOSITE MATERIAL AND METAL MATRIX COMPOSITE BULK**

[] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, 1. Industrial Technology Research Institute
of No. 195, Sec. 4, Chung Hsing Rd., Chutung, Hsinchu
31040, Taiwan, R. O. C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Li-Shing Chou Date: 13/8/2019

Sole or First Joint Inventor: Li-Shing Chou

Signature: Chih-Chao Yang Date: 13/8/2019

Second Joint Inventor (if any): Chih-Chao Yang

Signature: Chi-San Chen Date: 13/8/2019

Third Joint Inventor (if any): Chi-San Chen

Signature: Chih-Jung Weng Date: 13/8/2019

Fourth Joint Inventor (if any): Chih-Jung Weng

Signature: Heng-Yi Tsai Date: 13/08/2019

Fifth Joint Inventor (if any): Heng-Yi Tsai